

# 74LVC1G32

## Single 2-input OR gate

Rev. 10 — 4 September 2012

Product data sheet

## 1. General description

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The 74LVC1G32 provides one 2-input OR function.

Inputs can be driven from either 3.3 V or 5 V devices. This feature allows the use of these devices as translators in mixed 3.3 V and 5 V applications.

Schmitt trigger action at all inputs makes the circuit tolerant of slower input rise and fall time.

This device is fully specified for partial power-down applications using  $I_{OFF}$ .

The  $I_{OFF}$  circuitry disables the output, preventing the damaging backflow current through the device when it is powered down.

## 2. Features and benefits

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- Wide supply voltage range from 1.65 V to 5.5 V
- High noise immunity
- Complies with JEDEC standard:
  - ◆ JESD8-7 (1.65 V to 1.95 V)
  - ◆ JESD8-5 (2.3 V to 2.7 V)
  - ◆ JESD8-B/JESD36 (2.7 V to 3.6 V)
- ESD protection:
  - ◆ HBM JESD22-A114F exceeds 2000 V
  - ◆ MM JESD22-A115-A exceeds 200 V
- $\pm 24$  mA output drive ( $V_{CC} = 3.0$  V)
- CMOS low power consumption
- Latch-up performance exceeds 250 mA
- Direct interface with TTL levels
- Inputs accept voltages up to 5 V
- Multiple package options
- Specified from  $-40$  °C to  $+85$  °C and  $-40$  °C to  $+125$  °C



3. Ordering information

Table 1. Ordering information

Type number	Package			
	Temperature range	Name	Description	Version
74LVC1G32GW	−40 °C to +125 °C	TSSOP5	plastic thin shrink small outline package; 5 leads; body width 1.25 mm	SOT353-1
74LVC1G32GV	−40 °C to +125 °C	SC-74A	plastic surface-mounted package; 5 leads	SOT753
74LVC1G32GM	−40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1.45 × 0.5 mm	SOT886
74LVC1G32GF	−40 °C to +125 °C	XSON6	plastic extremely thin small outline package; no leads; 6 terminals; body 1 × 1 × 0.5 mm	SOT891
74LVC1G32GN	−40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 0.9 × 1.0 × 0.35 mm	SOT1115
74LVC1G32GS	−40 °C to +125 °C	XSON6	extremely thin small outline package; no leads; 6 terminals; body 1.0 × 1.0 × 0.35 mm	SOT1202
74LVC1G32GX	−40 °C to +125 °C	X2SON5	X2SON5: plastic thermal enhanced extremely thin small outline package; no leads; 5 terminals; body 0.8 × 0.8 × 0.35 mm	SOT1226

4. Marking

Table 2. Marking

Type number	Marking code <sup>[1]</sup>
74LVC1G32GW	VG
74LVC1G32GV	V32
74LVC1G32GM	VG
74LVC1G32GF	VG
74LVC1G32GN	VG
74LVC1G32GS	VG
74LVC1G32GX	VG

[1] The pin 1 indicator is located on the lower left corner of the device, below the marking code.

5. Functional diagram

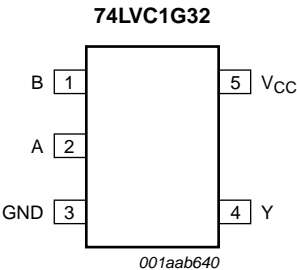
Fig 1. Logic symbol

Fig 2. IEC logic symbol

Fig 3. Logic diagram

6. Pinning information

6.1 Pinning



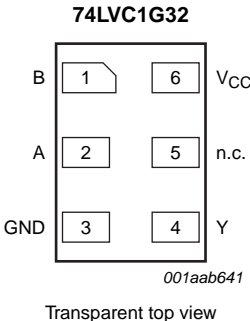
**74LVC1G32**

B 1 5 V<sub>CC</sub>

A 2

GND 3 4 Y

001aab640



**74LVC1G32**

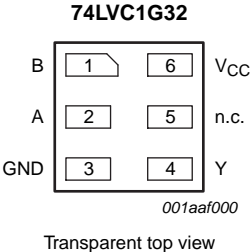
B 1 6 V<sub>CC</sub>

A 2 5 n.c.

GND 3 4 Y

001aab641

Transparent top view



**74LVC1G32**

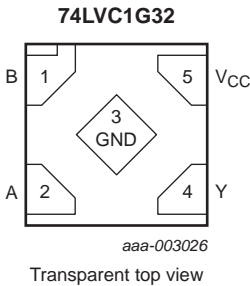
B 1 6 V<sub>CC</sub>

A 2 5 n.c.

GND 3 4 Y

001aaf000

Transparent top view



**74LVC1G32**

B 1 5 V<sub>CC</sub>

A 2 4 Y

3 GND

aaa-003026

Transparent top view

**Fig 4. Pin configuration SOT353-1 and SOT753**

**Fig 5. Pin configuration SOT886**

**Fig 6. Pin configuration SOT891, SOT1115 and SOT1202**

**Fig 7. Pin configuration SOT1226 (X2SON5)**

6.2 Pin description

Table 3. Pin description

Symbol	Pin		Description
	TSSOP5 and X2SON5	XSON6	
B	1	1	data input
A	2	2	data input
GND	3	3	ground (0 V)
Y	4	4	data output
n.c.	-	5	not connected
V <sub>CC</sub>	5	6	supply voltage

## 7. Functional description

Table 4. Function table<sup>[1]</sup>

Input		Output
A	B	Y
L	L	L
L	H	H
H	L	H
H	H	H

[1] H = HIGH voltage level; L = LOW voltage level

## 8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{CC}$	supply voltage		-0.5	+6.5	V
$I_{IK}$	input clamping current	$V_I < 0$ V	-50	-	mA
$V_I$	input voltage		<sup>[1]</sup> -0.5	+6.5	V
$I_{OK}$	output clamping current	$V_O > V_{CC}$ or $V_O < 0$ V	-	±50	mA
$V_O$	output voltage	Active mode	<sup>[1][2]</sup> -0.5	$V_{CC} + 0.5$	V
		Power-down mode	<sup>[1][2]</sup> -0.5	+6.5	V
$I_O$	output current	$V_O = 0$ V to $V_{CC}$	-	±50	mA
$I_{CC}$	supply current		-	100	mA
$I_{GND}$	ground current		-100	-	mA
$P_{tot}$	total power dissipation	$T_{amb} = -40$ °C to +125 °C	<sup>[3]</sup> -	250	mW
$T_{stg}$	storage temperature		-65	+150	°C

[1] The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

[2] When  $V_{CC} = 0$  V (Power-down mode), the output voltage can be 5.5 V in normal operation.

[3] For TSSOP5 and SC-74A packages: above 87.5 °C the value of  $P_{tot}$  derates linearly with 4.0 mW/K.  
For XSON6 and X2SON5 packages: above 118 °C the value of  $P_{tot}$  derates linearly with 7.8 mW/K.

## 9. Recommended operating conditions

**Table 6. Recommended operating conditions**

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$V_{CC}$	supply voltage		1.65	-	5.5	V
$V_I$	input voltage		0	-	5.5	V
$V_O$	output voltage	Active mode	0	-	$V_{CC}$	V
		$V_{CC} = 0$ V; Power-down mode	0	-	5.5	V
$T_{amb}$	ambient temperature		-40	-	+125	°C
$\Delta t/\Delta V$	input transition rise and fall rate	$V_{CC} = 1.65$ V to 2.7 V	-	-	20	ns/V
		$V_{CC} = 2.7$ V to 5.5 V	-	-	10	ns/V

## 10. Static characteristics

**Table 7. Static characteristics**

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	-40 °C to +85 °C			-40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$V_{IH}$	HIGH-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	$0.65 \times V_C$ c	-	-	$0.65 \times V_C$ c	-	V
		$V_{CC} = 2.3$ V to 2.7 V	1.7	-	-	1.7	-	V
		$V_{CC} = 2.7$ V to 3.6 V	2.0	-	-	2.0	-	V
		$V_{CC} = 4.5$ V to 5.5 V	$0.7 \times V_{CC}$	-	-	$0.7 \times V_{CC}$	-	V
$V_{IL}$	LOW-level input voltage	$V_{CC} = 1.65$ V to 1.95 V	-	-	$0.35 \times V_{CC}$	-	$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3$ V to 2.7 V	-	-	0.7	-	0.7	V
		$V_{CC} = 2.7$ V to 3.6 V	-	-	0.8	-	0.8	V
		$V_{CC} = 4.5$ V to 5.5 V	-	-	$0.3 \times V_{CC}$	-	$0.3 \times V_{CC}$	V
$V_{OH}$	HIGH-level output voltage	$V_I = V_{IH}$ or $V_{IL}$						
		$I_O = -100$ $\mu$ A; $V_{CC} = 1.65$ V to 5.5 V	$V_{CC} - 0.1$	-	-	$V_{CC} - 0.1$	-	V
		$I_O = -4$ mA; $V_{CC} = 1.65$ V	1.2	-	-	0.95	-	V
		$I_O = -8$ mA; $V_{CC} = 2.3$ V	1.9	-	-	1.7	-	V
		$I_O = -12$ mA; $V_{CC} = 2.7$ V	2.2	-	-	1.9	-	V
		$I_O = -24$ mA; $V_{CC} = 3.0$ V	2.3	-	-	2.0	-	V
$V_{OL}$	LOW-level output voltage	$V_I = V_{IH}$ or $V_{IL}$						
		$I_O = 100$ $\mu$ A; $V_{CC} = 1.65$ V to 5.5 V	-	-	0.10	-	0.10	V
		$I_O = 4$ mA; $V_{CC} = 1.65$ V	-	-	0.45	-	0.70	V
		$I_O = 8$ mA; $V_{CC} = 2.3$ V	-	-	0.30	-	0.45	V
		$I_O = 12$ mA; $V_{CC} = 2.7$ V	-	-	0.40	-	0.60	V
		$I_O = 24$ mA; $V_{CC} = 3.0$ V	-	-	0.55	-	0.80	V
		$I_O = 32$ mA; $V_{CC} = 4.5$ V	-	-	0.55	-	0.80	V

**Table 7.** Static characteristics ...continued

At recommended operating conditions. Voltages are referenced to GND (ground = 0 V).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$I_I$	input leakage current	$V_I = 5.5 \text{ V}$ or GND; $V_{CC} = 0 \text{ V}$ to 5.5 V	-	$\pm 0.1$	$\pm 5$	-	$\pm 100$	$\mu\text{A}$
$I_{OFF}$	power-off leakage current	$V_{CC} = 0 \text{ V}$ ; $V_I$ or $V_O = 5.5 \text{ V}$	-	$\pm 0.1$	$\pm 10$	-	$\pm 200$	$\mu\text{A}$
$I_{CC}$	supply current	$V_I = 5.5 \text{ V}$ or GND; $I_O = 0 \text{ A}$ ; $V_{CC} = 1.65 \text{ V}$ to 5.5 V	-	0.1	10	-	200	$\mu\text{A}$
$\Delta I_{CC}$	additional supply current	per pin; $V_{CC} = 2.3 \text{ V}$ to 5.5 V; $V_I = V_{CC} - 0.6 \text{ V}$ ; $I_O = 0 \text{ A}$	-	5	500	-	5000	$\mu\text{A}$
$C_I$	input capacitance	$V_{CC} = 3.3 \text{ V}$ ; $V_I = \text{GND}$ to $V_{CC}$	-	5	-	-	-	pF

[1] All typical values are measured at  $V_{CC} = 3.3 \text{ V}$  and  $T_{amb} = 25 \text{ °C}$ .

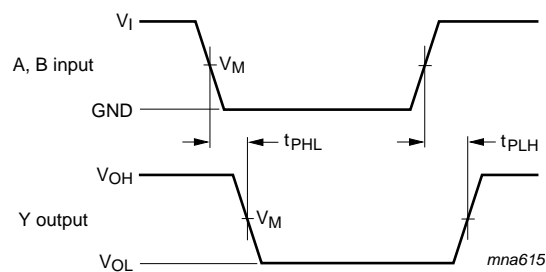
## 11. Dynamic characteristics

**Table 8.** Dynamic characteristicsVoltages are referenced to GND (ground = 0 V); for load circuit see [Figure 9](#).

Symbol	Parameter	Conditions	–40 °C to +85 °C			–40 °C to +125 °C		Unit
			Min	Typ <sup>[1]</sup>	Max	Min	Max	
$t_{pd}$	propagation delay	A, B to Y; see <a href="#">Figure 8</a> <sup>[2]</sup>						
		$V_{CC} = 1.65 \text{ V}$ to 1.95 V	1.0	3.1	8.0	1.0	10.5	ns
		$V_{CC} = 2.3 \text{ V}$ to 2.7 V	0.5	2.1	5.5	0.5	7.0	ns
		$V_{CC} = 2.7 \text{ V}$	0.5	2.5	5.5	0.5	7.0	ns
		$V_{CC} = 3.0 \text{ V}$ to 3.6 V	0.5	2.1	4.5	0.5	6.0	ns
		$V_{CC} = 4.5 \text{ V}$ to 5.5 V	0.5	1.7	4.0	0.5	5.5	ns
$C_{PD}$	power dissipation capacitance	$V_I = \text{GND}$ to $V_{CC}$ ; $V_{CC} = 3.3 \text{ V}$ <sup>[3]</sup>	-	16	-	-	-	pF

[1] Typical values are measured at  $T_{amb} = 25 \text{ °C}$  and  $V_{CC} = 1.8 \text{ V}$ , 2.5 V, 2.7 V, 3.3 V and 5.0 V respectively.[2]  $t_{pd}$  is the same as  $t_{PLH}$  and  $t_{PHL}$ .[3]  $C_{PD}$  is used to determine the dynamic power dissipation ( $P_D$  in  $\mu\text{W}$ ). $P_D = (C_{PD} \times V_{CC}^2 \times f_i \times N) + (C_L \times V_{CC}^2 \times f_o)$  where: $V_{CC}$  = supply voltage in V, $f_i$  = input frequency in MHz, $N$  = number of inputs switching, $C_L$  = output load capacitance in pF, $f_o$  = output frequency in MHz.

## 12. AC waveforms

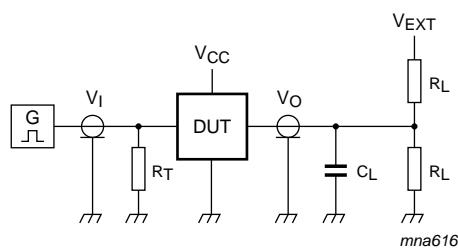


Measurement points are given in [Table 9](#).  
 $V_{OL}$  and  $V_{OH}$  are typical output voltage levels that occur with the output load.

**Fig 8. The input A, B to output Y propagation delays**

**Table 9. Measurement points**

Supply voltage	Input	Output
$V_{CC}$	$V_M$	$V_M$
1.65 V to 1.95 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.3 V to 2.7 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$
2.7 V	1.5 V	1.5 V
3.0 V to 3.6 V	1.5 V	1.5 V
4.5 V to 5.5 V	$0.5 \times V_{CC}$	$0.5 \times V_{CC}$



Test data is given in [Table 10](#).  
Definitions for test circuit:  
 $R_L$  = Load resistance.  
 $C_L$  = Load capacitance including jig and probe capacitance.  
 $R_T$  = Termination resistance; should be equal to the output impedance  $Z_o$  of the pulse generator.  
 $V_{EXT}$  = External voltage for measuring switching times.

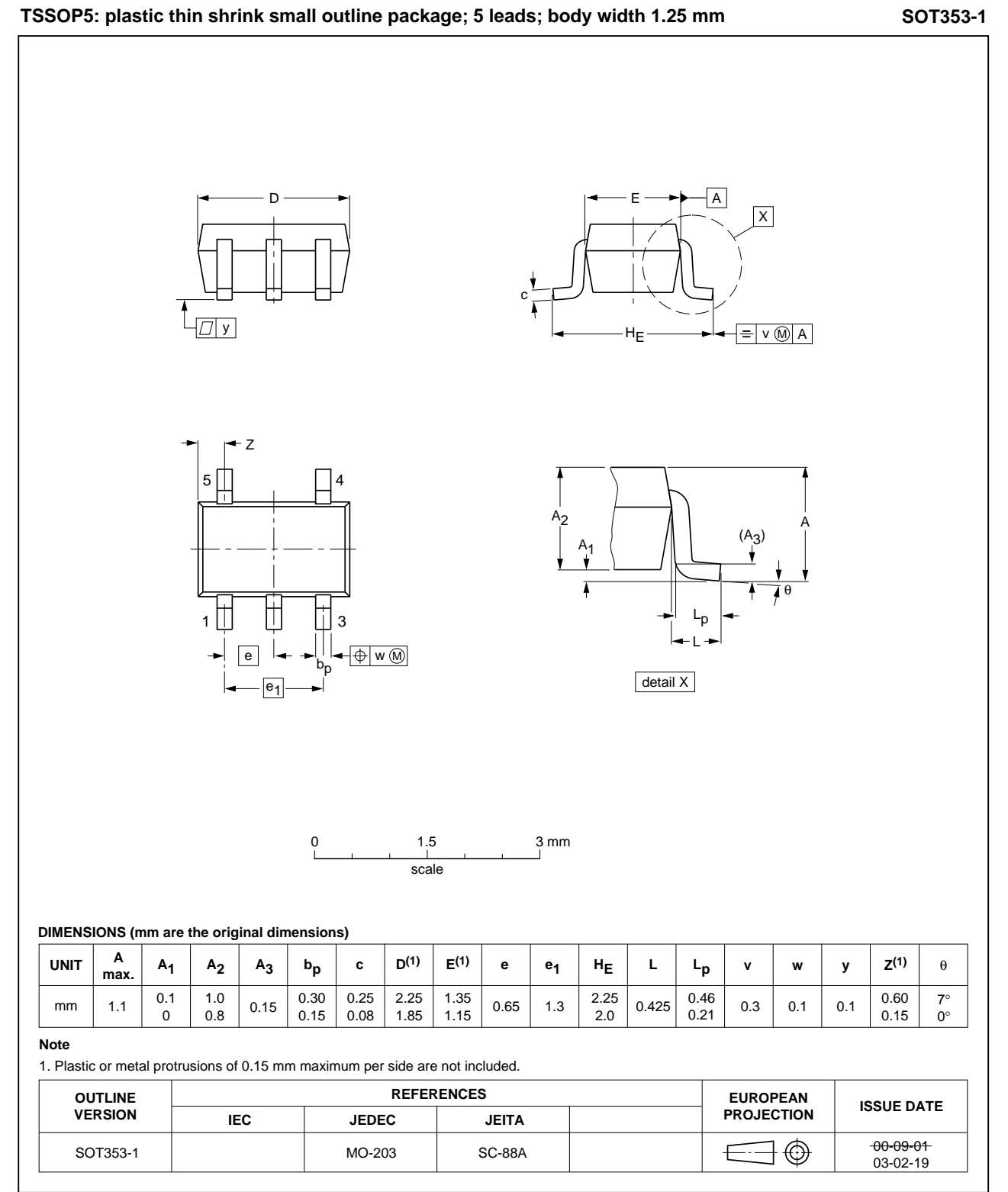
**Fig 9. Test circuit for measuring switching times**

Table 10. Test data

Supply voltage	Input		Load		V <sub>EXT</sub>
V <sub>CC</sub>	V <sub>I</sub>	t <sub>r</sub> = t <sub>f</sub>	C <sub>L</sub>	R <sub>L</sub>	t <sub>PLH</sub> , t <sub>PHL</sub>
1.65 V to 1.95 V	V <sub>CC</sub>	≤ 2.0 ns	30 pF	1 kΩ	open
2.3 V to 2.7 V	V <sub>CC</sub>	≤ 2.0 ns	30 pF	500 Ω	open
2.7 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open
3.0 V to 3.6 V	2.7 V	≤ 2.5 ns	50 pF	500 Ω	open
4.5 V to 5.5 V	V <sub>CC</sub>	≤ 2.5 ns	50 pF	500 Ω	open



13. Package outline



Plastic surface-mounted package; 5 leads

SOT753

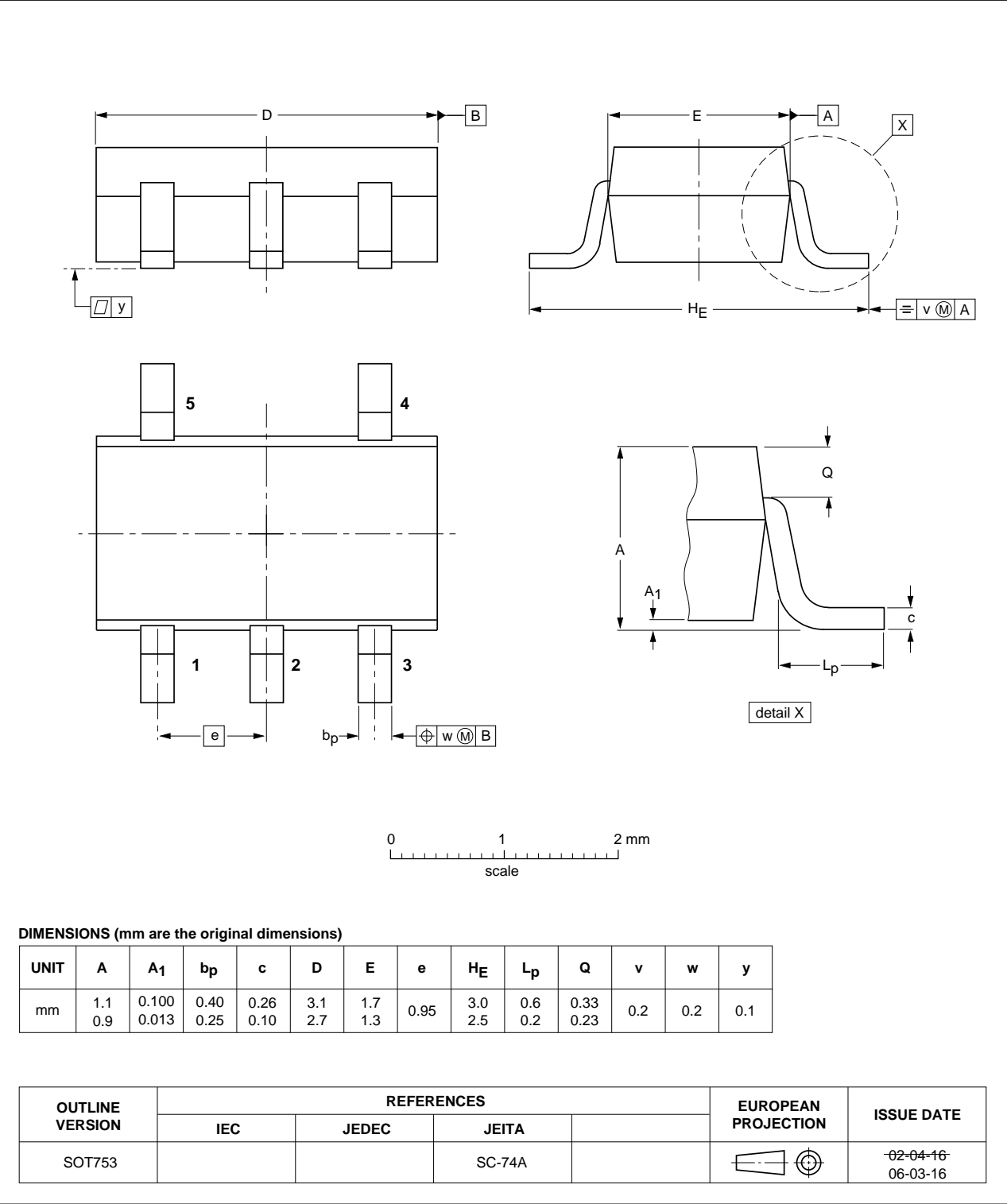


Fig 11. Package outline SOT753 (SC-74A)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1.45 x 0.5 mm

SOT886

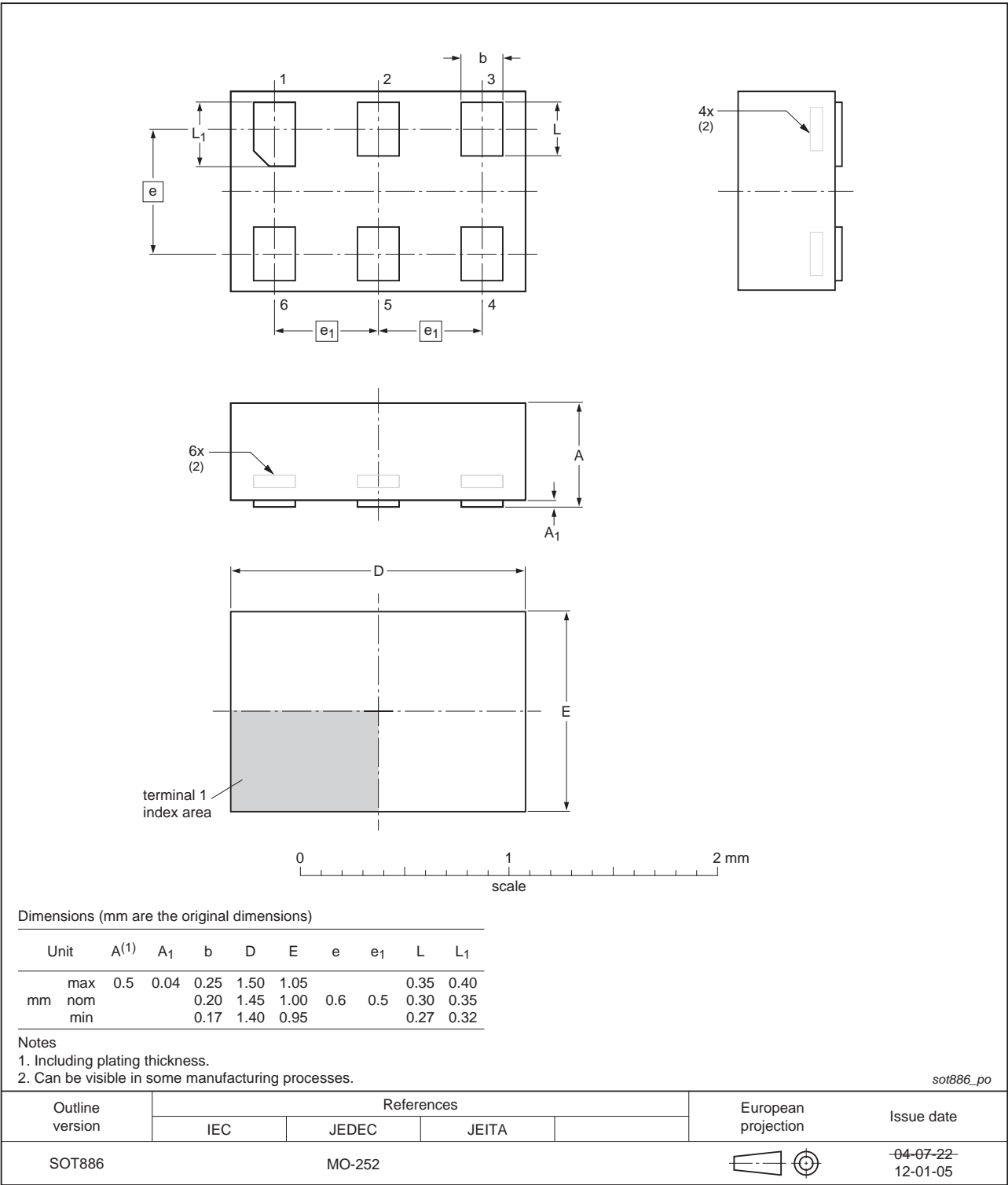


Fig 12. Package outline SOT886 (XSON6)

XSON6: plastic extremely thin small outline package; no leads; 6 terminals; body 1 x 1 x 0.5 mm

SOT891

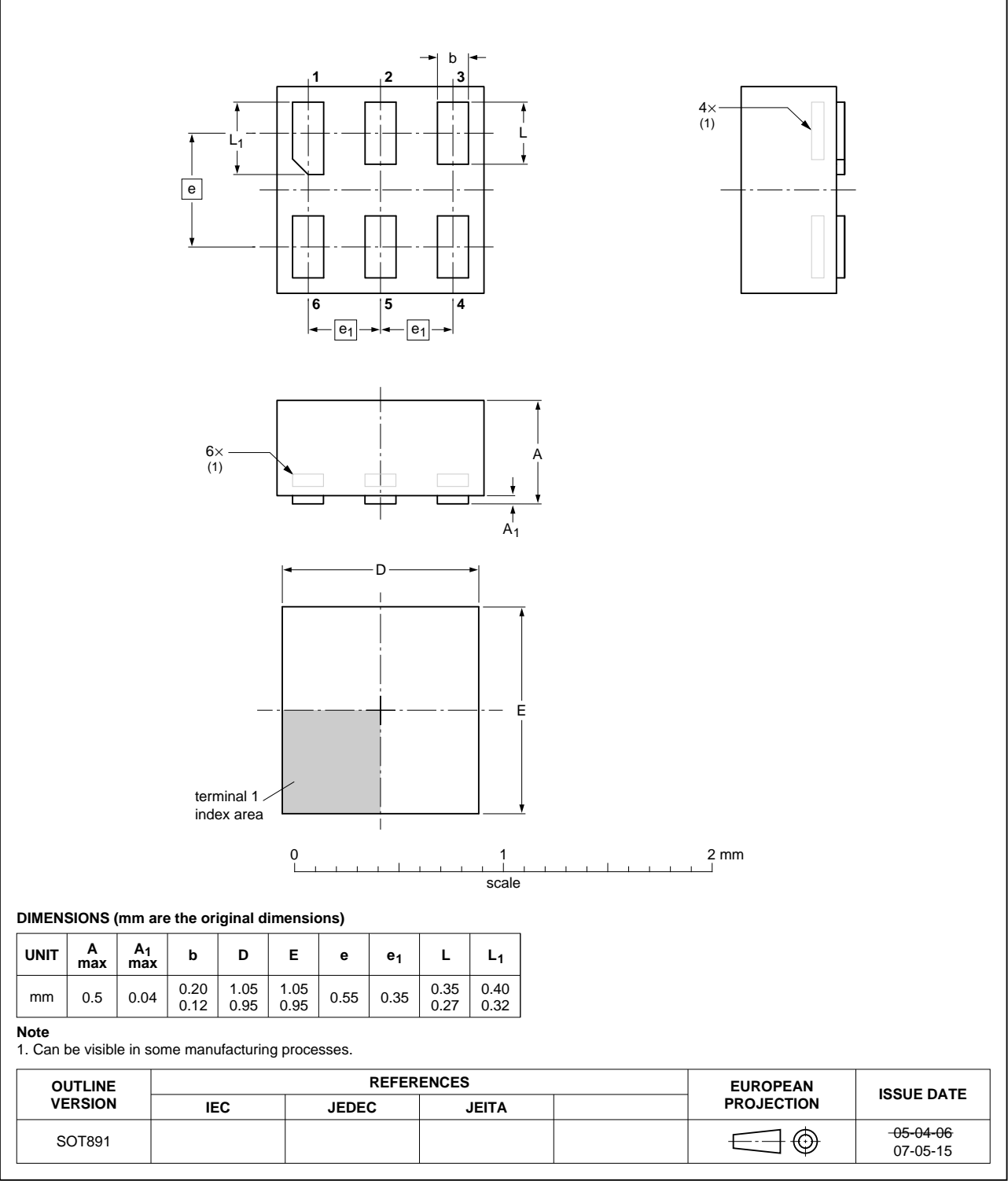
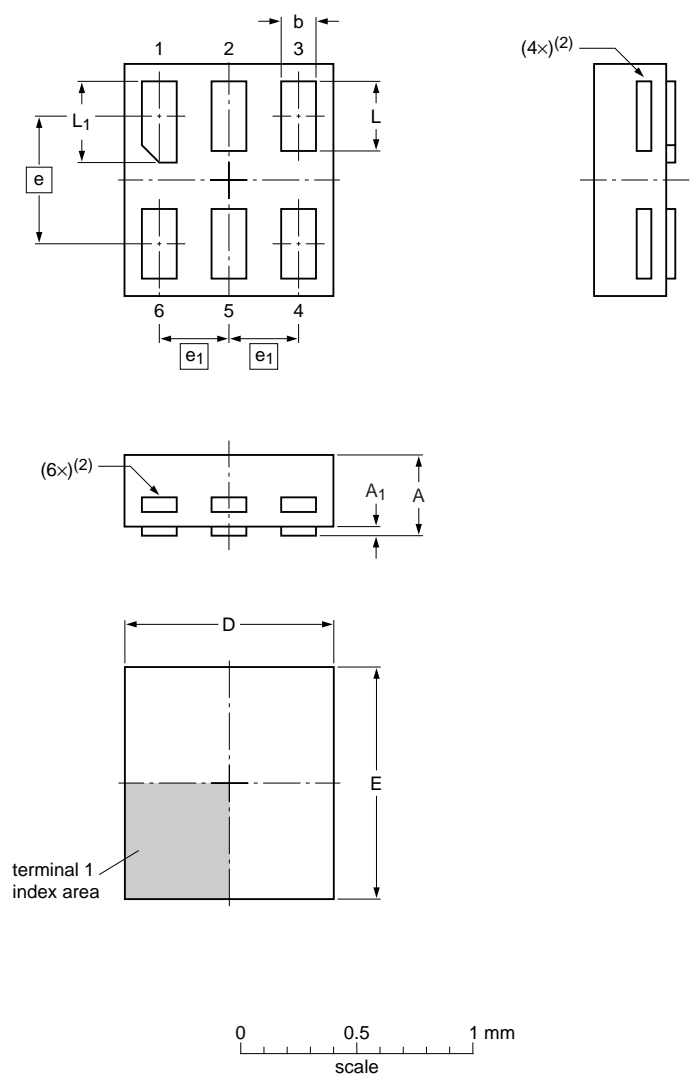


Fig 13. Package outline SOT891 (XSON6)

XSON6: extremely thin small outline package; no leads;  
6 terminals; body 0.9 x 1.0 x 0.35 mm

SOT1115



Dimensions

Unit	A <sup>(1)</sup>	A <sub>1</sub>	b	D	E	e	e <sub>1</sub>	L	L <sub>1</sub>
mm	max	0.35	0.04	0.20	0.95	1.05		0.35	0.40
	nom			0.15	0.90	1.00	0.55	0.30	0.35
	min			0.12	0.85	0.95		0.27	0.32

- Note
1. Including plating thickness.
  2. Visible depending upon used manufacturing technology.

sot1115\_po

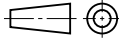
Outline version	References				European projection	Issue date
	IEC	JEDEC	JEITA			
SOT1115						<del>10-04-02</del> 10-04-07

Fig 14. Package outline SOT1115 (XSON6)

XSON6: extremely thin small outline package; no leads;  
6 terminals; body 1.0 x 1.0 x 0.35 mm

SOT1202

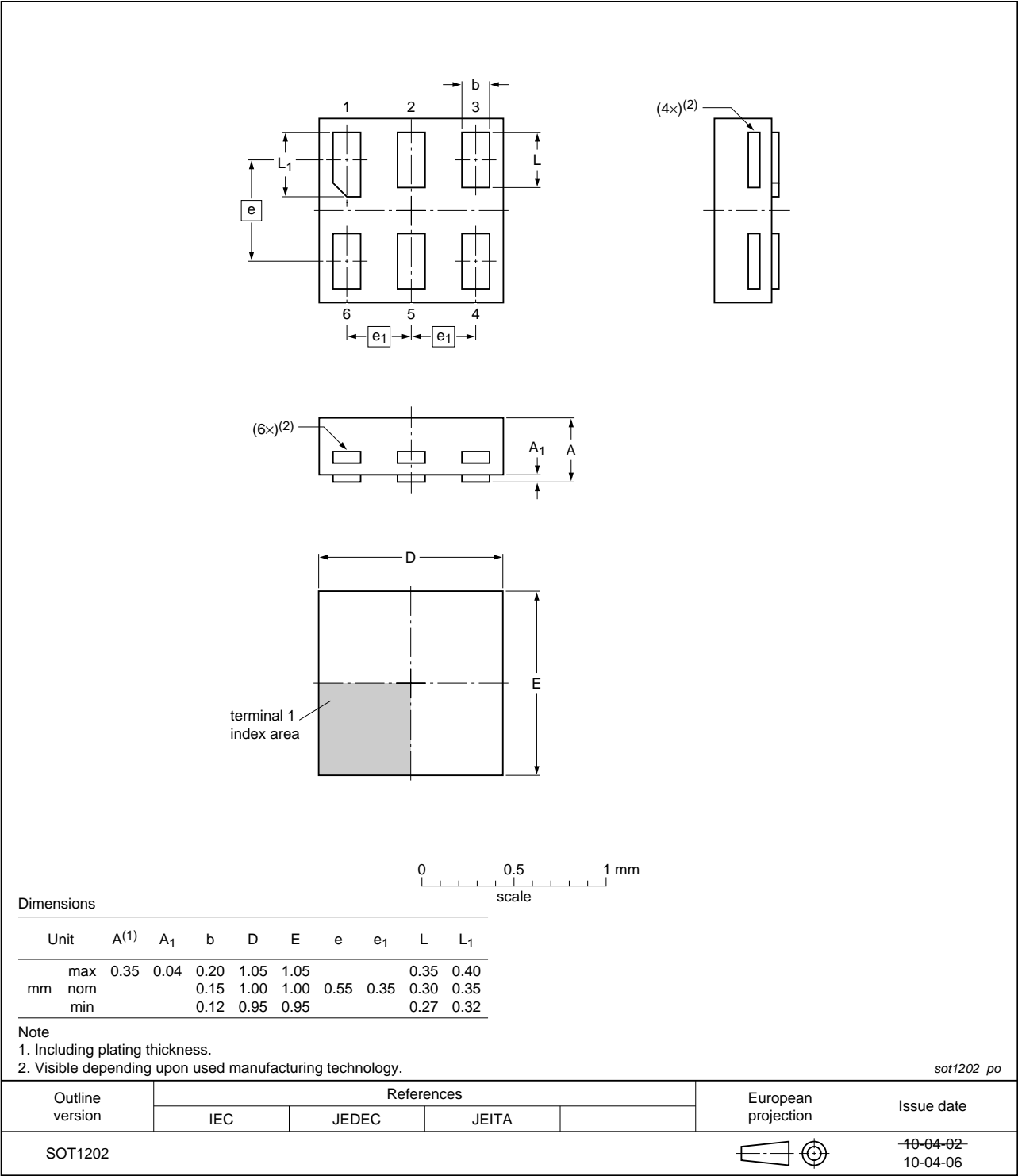


Fig 15. Package outline SOT1202 (XSON6)

X2SON5: plastic thermal enhanced extremely thin small outline package; no leads;  
5 terminals; body 0.8 x 0.8 x 0.35 mm

SOT1226

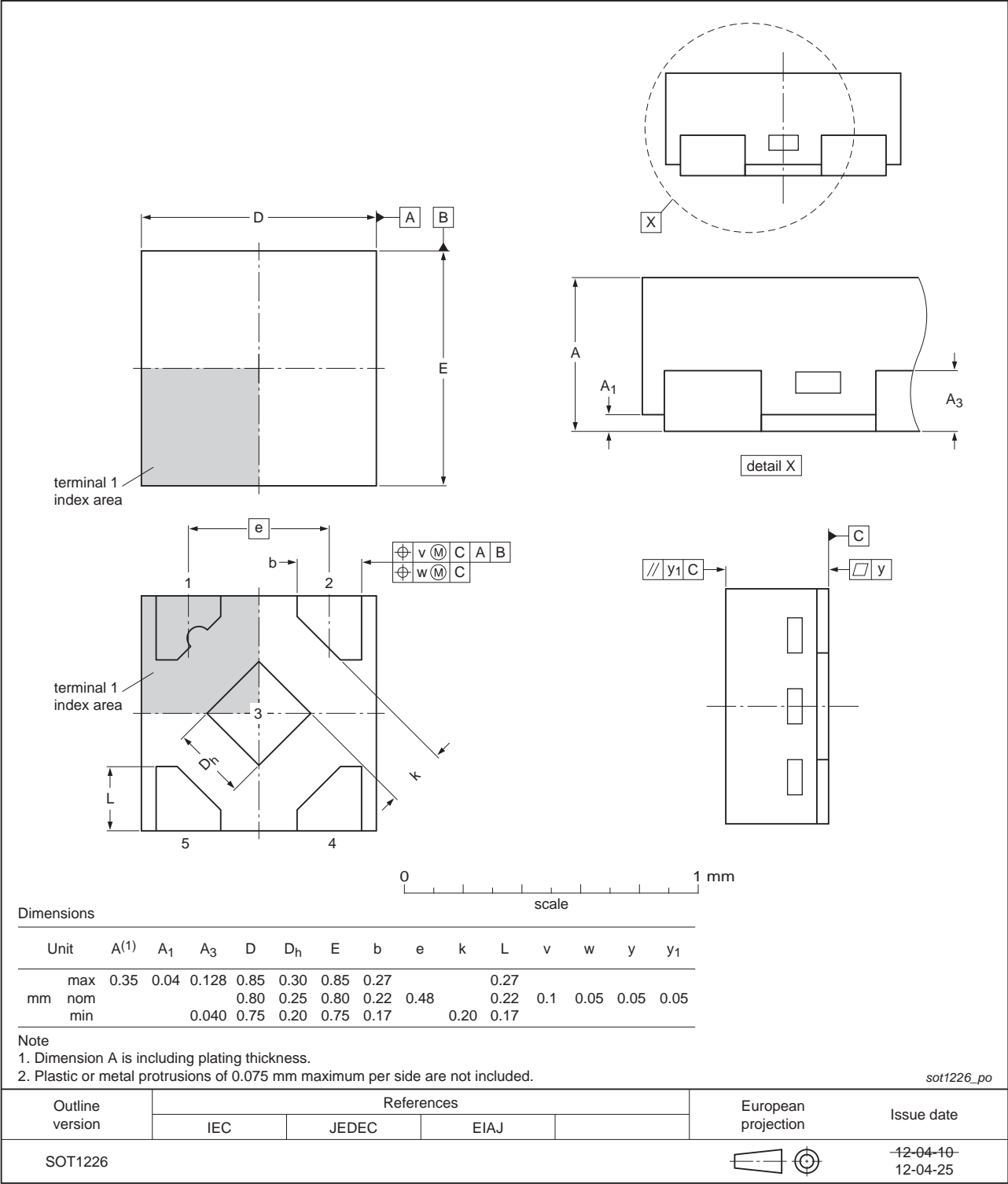


Fig 16. Package outline SOT1226 (X2SON5)

## 14. Abbreviations

Table 11. Abbreviations

Acronym	Description
CMOS	Complementary Metal Oxide Semiconductor
DUT	Device Under Test
ESD	ElectroStatic Discharge
HBM	Human Body Model
MM	Machine Model
TTL	Transistor-Transistor Logic

## 15. Revision history

Table 12. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
74LVC1G32 v.10	20120904	Product data sheet	-	74LVC1G32 v.9
Modifications:	• Package outline drawing of SOT1226 ( <a href="#">Figure 16</a> ) modified.			
74LVC1G32 v.9	20120412	Product data sheet	-	74LVC1G32 v.8
Modifications:	• Added type number 74LVC1G32GX (SOT1226) • Package outline drawing of SOT886 ( <a href="#">Figure 12</a> ) modified.			
74LVC1G32 v.8	20111206	Product data sheet	-	74LVC1G32 v.7
Modifications:	• Legal pages updated.			
74LVC1G32 v.7	20101020	Product data sheet	-	74LVC1G32 v.6
74LVC1G32 v.6	20070802	Product data sheet	-	74LVC1G32 v.5
74LVC1G32 v.5	20060619	Product data sheet	-	74LVC1G32 v.4
74LVC1G32 v.4	20040915	Product specification	-	74LVC1G32 v.3
74LVC1G32 v.3	20021115	Product specification	-	74LVC1G32 v.2
74LVC1G32 v.2	20020521	Product specification	-	74LVC1G32 v.1
74LVC1G32 v.1	20001121	Product specification	-	-



## 16. Legal information

### 16.1 Data sheet status

Document status <sup>[1][2]</sup>	Product status <sup>[3]</sup>	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL <http://www.nxp.com>.

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## 18. Contents

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<b>1</b>	<b>General description</b> .....	<b>1</b>
<b>2</b>	<b>Features and benefits</b> .....	<b>1</b>
<b>3</b>	<b>Ordering information</b> .....	<b>2</b>
<b>4</b>	<b>Marking</b> .....	<b>2</b>
<b>5</b>	<b>Functional diagram</b> .....	<b>2</b>
<b>6</b>	<b>Pinning information</b> .....	<b>3</b>
6.1	Pinning .....	3
6.2	Pin description .....	3
<b>7</b>	<b>Functional description</b> .....	<b>4</b>
<b>8</b>	<b>Limiting values</b> .....	<b>4</b>
<b>9</b>	<b>Recommended operating conditions</b> .....	<b>5</b>
<b>10</b>	<b>Static characteristics</b> .....	<b>5</b>
<b>11</b>	<b>Dynamic characteristics</b> .....	<b>6</b>
<b>12</b>	<b>AC waveforms</b> .....	<b>7</b>
<b>13</b>	<b>Package outline</b> .....	<b>9</b>
<b>14</b>	<b>Abbreviations</b> .....	<b>16</b>
<b>15</b>	<b>Revision history</b> .....	<b>16</b>
<b>16</b>	<b>Legal information</b> .....	<b>17</b>
16.1	Data sheet status .....	17
16.2	Definitions .....	17
16.3	Disclaimers .....	17
16.4	Trademarks .....	18
<b>17</b>	<b>Contact information</b> .....	<b>18</b>
<b>18</b>	<b>Contents</b> .....	<b>19</b>

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